

Report NO.: M000004000036

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC1R3SN04C
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.39%
Lead Frame	Copper	7440-50-8	97.52%	
	Iron	7439-89-6	2.35%	
	P	7723-14-0	0.08%	
	Plating Ag	7440-22-4	0.05%	
Clip	Copper	7440-50-8	97.57%	5.28%
	Iron	7439-89-6	2.35%	
	Phosphorus	7723-14-0	0.08%	
Solder	Lead	7439-92-1	85.00%	3.46%
	Tin	7440-31-5	4.35%	
	Silver	7440-22-4	2.15%	
	Butanediol mixture	107-88-0	7.50%	
	Modified castor oil	61788-85-0	1.00%	
Wire	Gold	7440-57-5	99.99%	2.30%
	Others	/	0.01%	
Mold Compound	Silica	60676-86-0	82.00%	49.81%
	Epoxy Resin	85954-11-6	10.00%	
	Phenol Resin	26834-02-6	7.50%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.90%	2.29%
	Other	/	0.10%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.